AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

1-6. (cancelled).

- 7. (currently amended) A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate, characterized in that a central surface average roughness "Sa" of the zirconia surface layer is from 10 to 40 μ m, and the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to $10\mu m$.
- 8. (currently amended) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia surface layer formed on the intermediate layer, characterized in that a central surface average roughness "Sa" of the zirconia surface layer is from 10 to 40 μ m, and the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80

to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to $10\mu m$.

- 9-10. (cancelled).
- 11. (currently amended) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia surface layer formed on the intermediate layer, characterized in that a wear resistance in a reciprocating wear test conducted in accordance with JIS-H8503 is from 10 to 200 (DS/mg), the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10µm bonded with each other by a sintering aid made of two or more metal oxides for increasing the wear resistance, and the intermediate layer includes coarse metal oxide particles having an average particle size from 30 to 500µm and fine metal oxide particles having an average particle size from 0.1 to 5µm which are solid-phase calcined.
 - 12. (cancelled).
- 13. (currently amended) A jig for calcining an electronic component comprising a substrate and a zirconia

surface layer formed on the substrate, characterized in that a thermal shock resistance Δ T (=T1-T2) is 400°C or more expressed as a temperature difference of rapid cooling which generates strength reduction in a rapid cooling bending test where the jog for calcining the electronic component is rapidly cooled from specified temperature T1 to T2, and metal oxides are used as a sintering aid for calcining the zirconia layer coated on the substrate surface, alumina intermediate layer coated on the substrate surface, and the zirconia layer coated on the alumina intermediate layer.

14. (currently amended) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia layer formed on the intermediate layer, characterized in that a thermal shock resistance Δ T is 400°C or more, and metal oxides are used as a sintering aid for calcining the zirconia layer coated on the substrate surface, alumina intermediate layer coated on the substrate surface, and the zirconia layer coated on the substrate surface, and the zirconia layer coated on the alumina intermediate layer.

15-22. (cancelled).